



Title of Change:	Copper wire conversion for LB1940T.	
Proposed first ship date:	16 November 2015	
Contact information:	Contact your local ON Semiconductor Sales Office or < Tsutomu Shimazaki@onsemi.com > < Takashi.Harashima@onsemi.com>< Takeshi2.Hoshino@onsemi.com>< Kazumi.Onda@onsemi.com> < Shinya Okada@onsemi.com>< Yoshiyuki Nunokawa@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office. < jun.hasunuma@onsemi.com>	
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Affected products will be identified with date code.	
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines	<input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose:		
This is an Initial Process Change Notification to announce Gold wire connecting chip and Lead will be changed to Copper wire. The electrical characteristic specification is not impacted of this change.		
Qualification Plan:		
Estimated date for qualification completion: 28 August 2015		
Package name : TSSOP20(225mil)		
Test Items	Test Condition	Test Time
High Temperature Operating Life	Tj=Tjmax,Vcc=Operatingmax	1000hrs
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended T	1000hrs
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	500cycles
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	50hrs
High Temperature Storage	Ta=150degC	1000hrs
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times
Notes:		
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD		
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.		
Judgment Criteria :		
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.		
List of Affected Standard Parts:		
Part Number	Qualification Vehicle	
LB1940T-TLM-H	LB1940T-TLM-H	